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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	19
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-LSSOP (0.220", 5.60mm Width)
Supplier Device Package	24-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f213g5dnsp-u0

1. Overview

1.1 Features

The R8C/3GD Group of single-chip MCUs incorporates the R8C CPU core, employing sophisticated instructions for a high level of efficiency. With 1 Mbyte of address space, and it is capable of executing instructions at high speed. In addition, the CPU core boasts a multiplier for high-speed operation processing.

Power consumption is low, and the supported operating modes allow additional power control. These MCUs are designed to maximize EMI/EMS performance.

Integration of many peripheral functions, including multifunction timer and serial interface, reduces the number of system components.

1.1.1 Applications

Electronic household appliances, office equipment, audio equipment, consumer equipment, etc.

Table 1.2 Specifications for R8C/3GD Group (2)

Item	Function	Specification
Flash Memory		<ul style="list-style-type: none"> • Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current consumption		Typ. 6.5mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2.0μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽¹⁾
Package		24-pin LSSOP Package code: PLSP0024JB-A (previous code: 24P2F-A)

Note:

1. Specify the D version if D version functions are to be used.

1.3 Block Diagram

Figure 1.2 shows a Block Diagram.

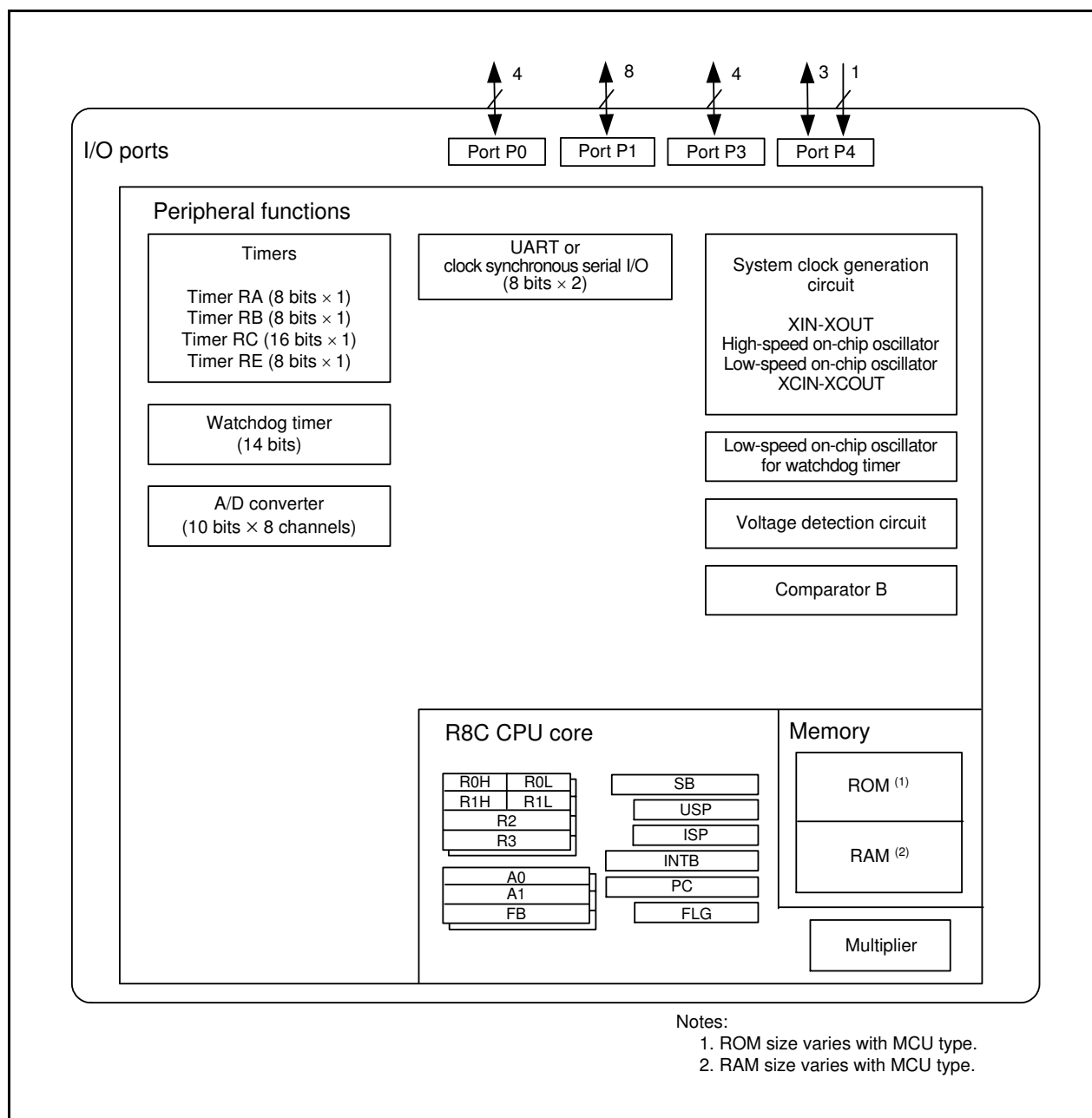


Figure 1.2 Block Diagram

Table 1.4 Pin Name Information by Pin Number

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules			
			Interrupt	Timer	Serial Interface	A/D Converter, Comparator B
1		P0_2		(TRCIOA/TRCTRG)		AN5
2		P0_1		(TRCIOA/TRCTRG)		AN6
3		P4_2				VREF
4	MODE					
5	RESET					
6	XOUT(XCOUT)	P4_7				
7	VSS/AVSS					
8	XIN(XCIN)	P4_6				
9	VCC/AVCC					
10		P3_7		TRAO	(RXD2/SCL2/ TXD2/SDA2)	
11		P3_5		(TRCIOD)	(CLK2)	
12		P3_4		(TRCIOC)	(RXD2/SCL2/ TXD2/SDA2)	IVREF3
13		P3_3	$\overline{\text{INT3}}$	(TRCCLK)	(CTS2/RTS2)	IVCMP3
14		P4_5	$\overline{\text{INT0}}$		(RXD2/SCL2)	$\overline{\text{ADTRG}}$
15		P1_7	$\overline{\text{INT1}}$	(TRAIO)		IVCMP1
16		P1_6			(CLK0)	IVREF1
17		P1_5	($\overline{\text{INT1}}$)	(TRAIO)	(RXD0)	
18		P1_4		(TRCCLK)	(TXD0)	
19		P1_3	$\overline{\text{KI3}}$	TRBO/TRCIOC)		AN11
20		P1_2	$\overline{\text{KI2}}$	(TRCIOB)		AN10
21		P1_1	$\overline{\text{KI1}}$	(TRCIOA/TRCTRG)		AN9
22		P1_0	$\overline{\text{KI0}}$	(TRCIOD)		AN8
23		P0_7		(TRCIOC)		AN0
24		P0_6		(TRCIOD)		AN1

Note:

1. Can be assigned to the pin in parentheses by a program.

1.5 Pin Functions

Table 1.5 lists Pin Functions.

Table 1.5 Pin Functions

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins ⁽¹⁾ . To use an external clock, input it to the XOUT pin and leave the XIN pin open.
XIN clock output	XOUT	I/O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between the XCIN and XCOUT pins ⁽¹⁾ . To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$, $\overline{\text{INT1}}$, $\overline{\text{INT3}}$	I	$\overline{\text{INT}}$ interrupt input pins. $\overline{\text{INT0}}$ is timer RB, and RC input pin.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRA0	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTR $\overline{\text{G}}$	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIO $\overline{\text{C}}$, TRCIOD	I/O	Timer RC I/O pins
Serial interface	CLK0, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD2	I	Serial data input pins
	TXD0, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	RTS2	O	Reception control output pin
	SCL2	I/O	I ² C mode clock I/O pin
	SDA2	I/O	I ² C mode data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter
A/D converter	AN0, AN1, AN5, AN6, AN8 to AN11	I	Analog input pins to A/D converter
	ADTR $\overline{\text{G}}$	I	A/D external trigger input pin
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O port	P0_1, P0_2, P0_6, P0_7, P1_0 to P1_7, P3_3 to P3_5, P3_7, P4_5 to P4_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. All ports can be used as LED drive ports.
Input port	P4_2	I	Input-only port

I: Input O: Output I/O: Input and output

Note:

1. Refer to the oscillator manufacturer for oscillation characteristics.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

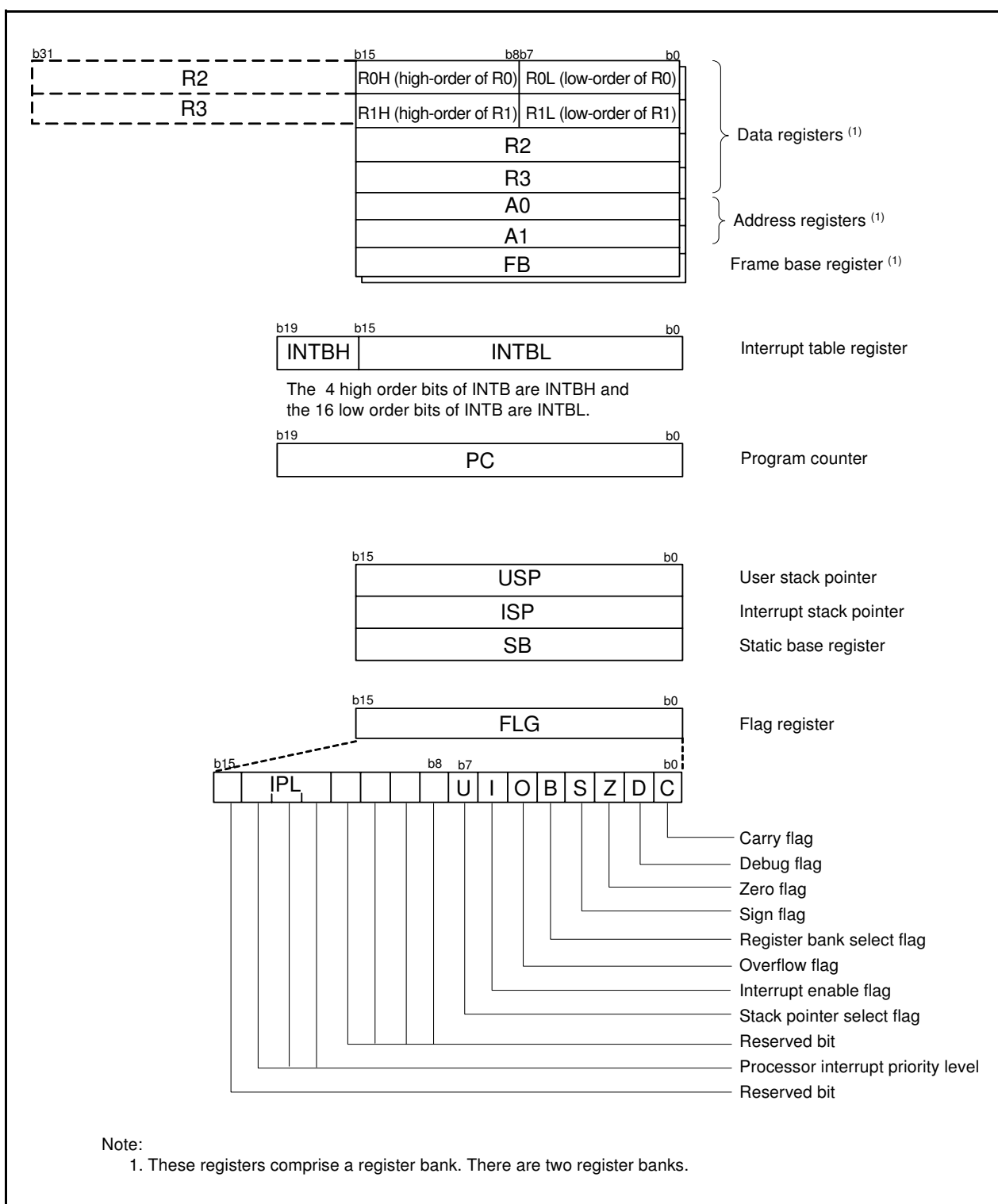


Figure 2.1 CPU Registers

Table 4.2 SFR Information (2) (1)

Address	Register	Symbol	After Reset
003Ah	Voltage Monitor 2 Circuit Control Register	VW2C	10000010b
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			
0040h			
0041h	Flash Memory Ready Interrupt Control Register	FMRDYIC	XXXXX000b
0042h			
0043h			
0044h			
0045h			
0046h			
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h			
0049h			
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh			
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h			
0054h			
0055h			
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	UART2 Bus Collision Detection Interrupt Control Register	U2BCNIC	XXXXX000b
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h	Voltage Monitor 1 Interrupt Control Register	VCMP1IC	XXXXX000b
0073h	Voltage Monitor 2 Interrupt Control Register	VCMP2IC	XXXXX000b
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.3 SFR Information (3) (1)

Address	Register	Symbol	After Reset
0080h			
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h			
0089h			
008Ah			
008Bh			
008Ch			
008Dh			
008Eh			
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit / Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit / Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit / Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART2 Transmit / Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh
00ABh			XXh
00ACh	UART2 Transmit / Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit / Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh
00AFh			XXh
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.7 SFR Information (7) (1)

Address	Register	Symbol	After Reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register	AIER	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h			
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Pull-Up Control Register 0	PUR0	00h
01E1h	Pull-Up Control Register 1	PUR1	00h
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h	Port P1 Drive Capacity Control Register	P1DRR	00h
01F1h			
01F2h	Drive Capacity Control Register 0	DRR0	00h
01F3h	Drive Capacity Control Register 1	DRR1	00h
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h			
01F8h	Comparator B Control Register 0	INTCMP	00h
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh			
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh			
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

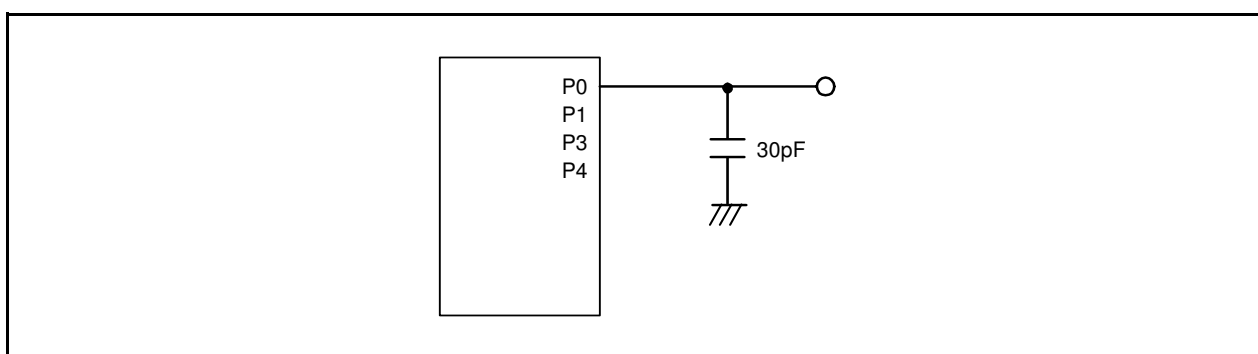


Figure 5.1 Ports P0, P1, P3, P4 Timing Measurement Circuit

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		Vref = AVCC		–	–	10	Bit
–	Absolute accuracy	10-bit mode	Vref = AVCC = 5.0 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±3	LSB
			Vref = AVCC = 3.3 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±5	LSB
			Vref = AVCC = 3.0 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±5	LSB
			Vref = AVCC = 2.2 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±5	LSB
		8-bit mode	Vref = AVCC = 5.0 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±2	LSB
			Vref = AVCC = 3.3 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±2	LSB
			Vref = AVCC = 3.0 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±2	LSB
			Vref = AVCC = 2.2 V	AN0, AN1, AN5, AN6, AN8 to AN11 input	–	–	±2	LSB
φAD	A/D conversion clock		4.0 ≤ Vref = AVCC ≤ 5.5 V ⁽²⁾		2	–	20	MHz
			3.2 ≤ Vref = AVCC ≤ 5.5 V ⁽²⁾		2	–	16	MHz
			2.7 ≤ Vref = AVCC ≤ 5.5 V ⁽²⁾		2	–	10	MHz
			2.2 ≤ Vref = AVCC ≤ 5.5 V ⁽²⁾		2	–	5	MHz
–	Tolerance level impedance				–	3	–	kΩ
tCONV	Conversion time	10-bit mode	Vref = AVCC = 5.0 V, φAD = 20 MHz		2.15	–	–	μs
		8-bit mode	Vref = AVCC = 5.0 V, φAD = 20 MHz		2.15	–	–	μs
tsAMP	Sampling time		φAD = 20 MHz		0.75	–	–	μs
IVref	Vref current		Vcc = 5 V, XIN = f1 = φAD = 20 MHz		–	45	–	μA
Vref	Reference voltage				2.2	–	AVcc	V
VIA	Analog input voltage ⁽³⁾				0	–	Vref	V
OCVREF	On-chip reference voltage		2 MHz ≤ φAD ≤ 4 MHz		1.19	1.34	1.49	V

Notes:

- $V_{CC}/AV_{CC} = V_{ref} = 2.2$ to 5.5 V , $V_{SS} = 0\text{ V}$ at $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
- The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
- When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.4 Comparator B Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{ref}	IVREF1, IVREF3 input reference voltage		0	—	$V_{CC} - 1.4$	V
V_I	IVCMP1, IVCMP3 input voltage		-0.3	—	$V_{CC} + 0.3$	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time ⁽²⁾	$V_I = V_{ref} \pm 100\text{ mV}$	—	0.1	—	μs
I_{CMP}	Comparator operating current	$V_{CC} = 5.0\text{ V}$	—	17.5	—	μA

Notes:

- $V_{CC} = 2.7$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
- When the digital filter is disabled.

Table 5.8 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet2	Voltage detection level Vdet2_0	At the falling of Vcc	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.10	—	V
—	Voltage detection 2 circuit response time ⁽²⁾	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	μs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

Notes:

1. The measurement condition is Vcc = 1.8 V to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version).
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.9 Power-on Reset Circuit (2)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
trth	External power Vcc rise gradient	⁽¹⁾	0	—	50000	mV/msec

Notes:

1. The measurement condition is T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.

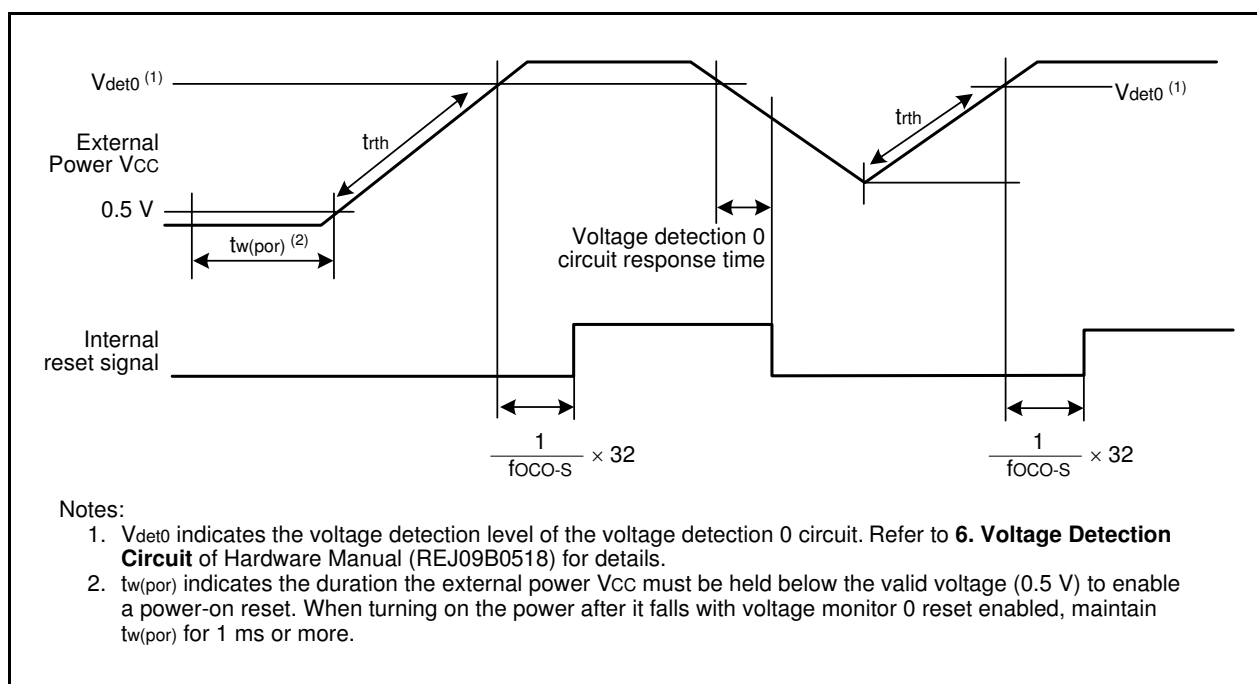
**Figure 5.3 Power-on Reset Circuit Electrical Characteristics**

Table 5.13 Electrical Characteristics (1) [4.2 V ≤ V_{CC} ≤ 5.5 V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High V _{CC} = 5V	I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity Low V _{CC} = 5V	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	V _{CC} = 5V	I _{OH} = -200 μA	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High V _{CC} = 5V	I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity Low V _{CC} = 5V	I _{OL} = 5 mA	—	—	2.0	V
		XOUT	V _{CC} = 5V	I _{OL} = 200 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT3, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOA, TRCIOC, TRCIOD, TRCTRG, TRCCLK, ADTRG, RXD0, RXD2, CLK0, CLK2			0.1	1.2	—	V
		RESET			0.1	1.2	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5.0V		—	—	5.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5.0V		—	—	-5.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5.0V		25	50	100	kΩ
R _{IXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R _{IXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

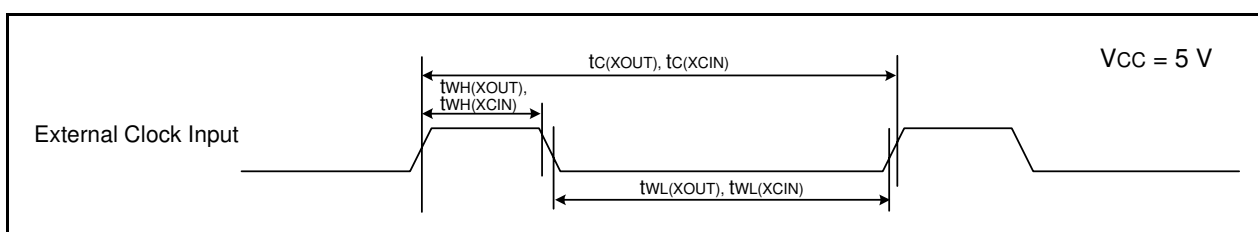
1. 4.2 V ≤ V_{CC} ≤ 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.14 Electrical Characteristics (2) [$3.3\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	6.5	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.3	12.5	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	3.6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.2	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 4 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-16 MSTTRC = 1	–	1	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	–	90	400	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division FMR27 = 1, VCA20 = 0	–	85	400	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division Program operation on RAM Flash memory off, FMSTP = 1, VCA20 = 0	–	47	–	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	–	15	100	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	–	4	90	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (peripheral clock off) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0, VCA20 = 1	–	3.5	–	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	2.0	5.0	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	5.0	–	μA

Timing Requirements (Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^{\circ}\text{C}$)**Table 5.15 External clock input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	24	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	24	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	μs
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	μs
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	μs

**Figure 5.4 External Clock Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.16 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	100	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	40	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	40	—	ns

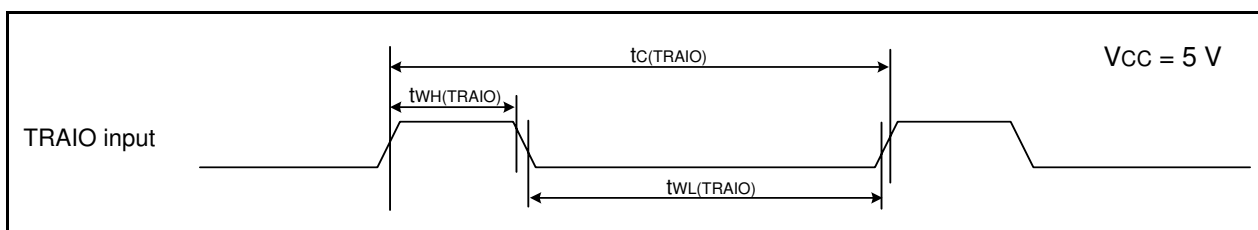
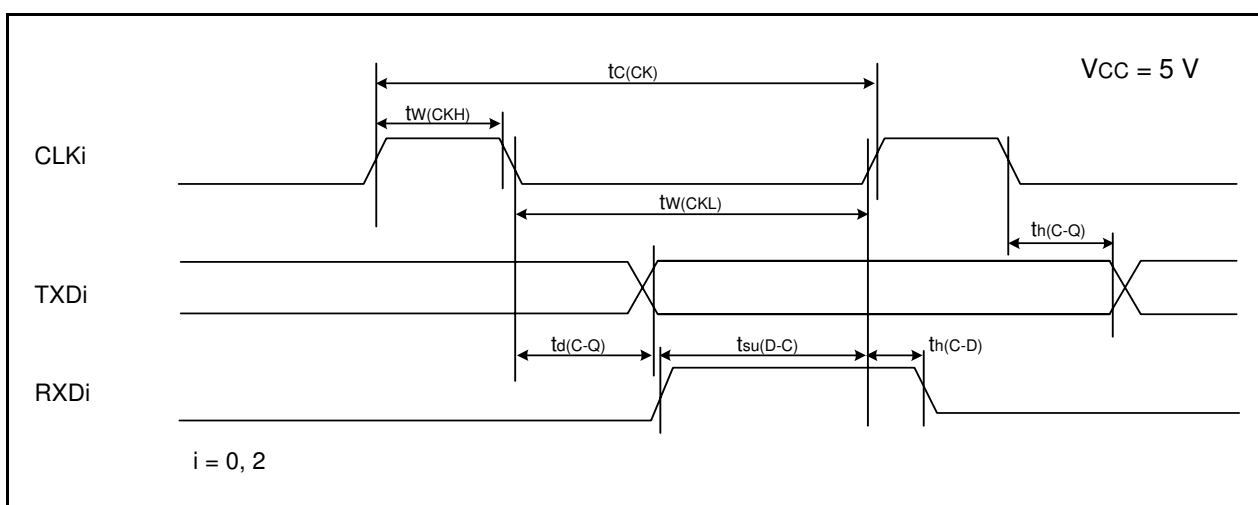
**Figure 5.5 TRAIO Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.17 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input "H" width	100	—	ns
$t_{w(CKL)}$	CLKi input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0, 2$ **Figure 5.6 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.18 External Interrupt \overline{INTi} ($i = 0, 1, 3$) Input, Key Input Interrupt \overline{Kli} ($i = 0$ to 3)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	\overline{INTi} input "H" width, \overline{Kli} input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	\overline{INTi} input "L" width, \overline{Kli} input "L" width	250 ⁽²⁾	—	ns

Notes:

1. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input HIGH width of either (1/digital filter clock frequency \times 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input LOW width of either (1/digital filter clock frequency \times 3) or the minimum value of standard, whichever is greater.

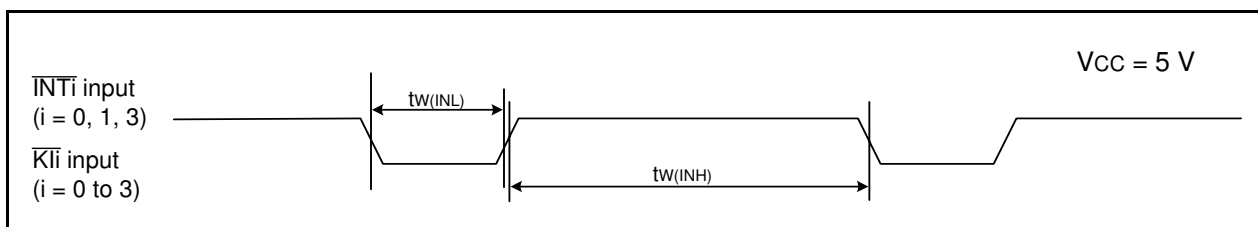
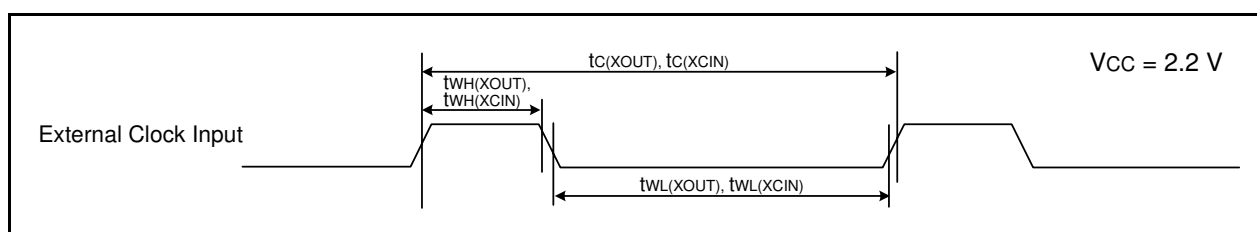
**Figure 5.7 Input Timing for External Interrupt \overline{INTi} and Key Input Interrupt \overline{Kli} when Vcc = 5 V**

Table 5.26 Electrical Characteristics (6) [$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

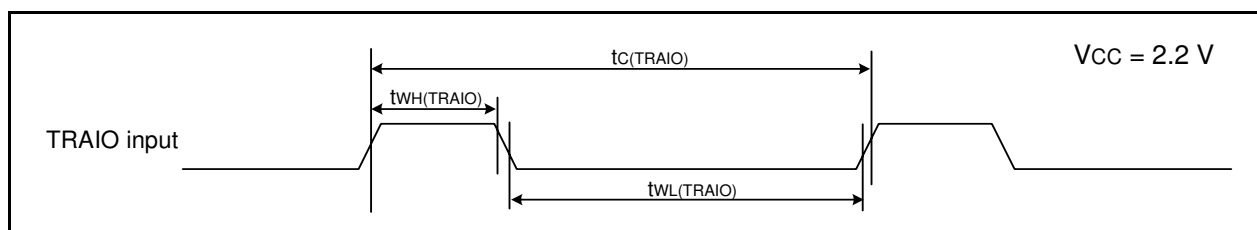
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current ($V_{CC} = 1.8\text{ to }2.7\text{ V}$) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	—	2.2	—	mA
				0.8	—	mA
		High-speed on-chip oscillator mode	—	2.5	10	mA
			—	1.7	—	mA
			—	1	—	mA
		Low-speed on-chip oscillator mode	—	90	300	μA
			—	80	350	μA
		Low-speed clock mode	—	40	—	μA
			—	—	—	μA
		Wait mode	—	15	90	μA
			—	4	80	μA
			—	3.5	—	μA
		Stop mode	—	2.0	5	μA
			—	5.0	—	μA

Timing Requirements (Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^{\circ}\text{C}$)**Table 5.27 External clock input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	200	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	90	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	90	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	μs
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	μs
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	μs

**Figure 5.12 External Clock Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.28 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	500	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	200	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	200	—	ns

**Figure 5.13 TRAIO Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

REVISION HISTORY	R8C/3GD Group Datasheet
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Rev.	Date	Description	
		Page	Summary
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1.00	Feb. 26, 2010	All pages 4 21 to 40	“Preliminary”, “Under development” deleted Table 1.3 revised “5. Electrical Characteristics” added

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